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DEPARTMENT OF DEFENSE

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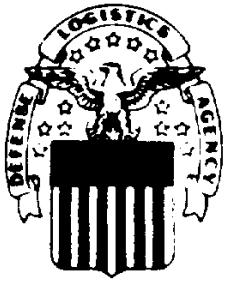
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INDUSTRIAL PLANT EQUIPMENT HANDBOOK

FSC 3670

**SPECIALIZED SEMICONDUCTOR,
MICROELECTRONIC CIRCUIT BOARD
MANUFACTURING MACHINERY**

August 1983



**DEFENSE LOGISTICS AGENCY
DEFENSE INDUSTRIAL PLANT EQUIPMENT CENTER
MEMPHIS, TENNESSEE 38114**

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DIPEC-T

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FOREWORD

This handbook is published under the authority of non Directive 4215.18, Management of Defense-Owned Industrial Plant Equipment (IPE), to identify IPE within Federal Supply Class (FSC) 3670 Specialized Semiconductor, Micro- electronic Circuit Board Manufacturing Machinery. All equipment within this FSC having an acquisition cost of \$3,000 or more and described in Section 1 and all similar equipment meeting the IPE definition will be reported. Items within this FSC not meeting the definition will not be reported. Items identified as IPE may be described according to Section 2 of this handbook. If an item cannot be related to a manufacturer's designation listed in Section 2, it should be described according to Section 3. Descriptions will be entered on DD Form 1419, non Industrial Plant Equipment Requisition, or DD Form 1342, DoD Property Record, or may be used for mechanized requisitioning or reporting. Policies and procedures for preparation and submission of DD Form(s) 1419 and 00 Form(s) 1342 are contained in DLAM 4215.1/AR 700-43/NAVSUP Pub 5009/A' 78-9, Management of Defense-Owned Industrial Plant Equipment (IPE).

Cumulative changes to this handbook will be published periodically and will include additional items/changes. New basic equipment types not previously published will be annotated by an asterisk (*) in Section 1.

Questions or comments regarding the contents of this handbook should be addressed to: Commander, Defense Industrial Plant Equipment Center, ATTN: DIPEC-T, Memphis, TN 38114.

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Section 1 - NOMENCLATURE TO PEC

Description	Size or Capacity	Plant Equipment Code	Descriptive Guide No.
ALIGNMENT MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	2.000" THRU 2.999" W AND LG MAX MASK	3670 3252 3321	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, AOTOMATIC	2. 100" THRU 2.199" MAX WAFER DIA 4.000" THRU 4.999" W X 6.000" THRU 6.999" LG MAX MASK 3.000" THRU 3.099" MAX WAFER DIA	3670 3263 5730	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, AUTOMATIC		3670 3263 0000	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, AUTOMATIC	4.000" THRU 4.999" W X 5.000" THRU 5.999" LG MAX MASK	3670 3263 5630	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, AUTOMATIC	4.000" THRU 4.999" W X 5.000" THRU 5.999" LG MAX MASK	3670 3263 5635	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, MANUALLY OPERATED		3670 3261 0000	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, MANUALLY OPERATED	2.000" THRU 2.999" W AND LO MAX MASK 1.200" THRU 1.299" MAX WAFER DIA	3670 3261 3312	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, MANUALLY OPERATED	2.000" THRU 2.999" W AND LG MAX MASK 1.500" THRU 1.599" MAX WAFER DIA	3670 3261 3315	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, MANUALLY OPERATED	2.000" THRU 2.999" W AND LG MAX MASK 2.000" THRU 2.099" MAX WAFER DIA	3670 3261 3320	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	6.000" THRU 6.999" W AND LG MAX MASK 3.500" THRU 3.599" MAX WAFER IDA	3670 3261 7744	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC		3670 3262 0000	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	2.000" THRU 2.999" W AND LG MAX MASK 1.500" THRU 1.599" MAX WAFER DIA	3670 3262 3315	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	2.000" THRU 2.999" W AND LG MAX MASK 2.000" THRU 2.099" MAX WAFER DIA	3670 3262 3320	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	4.000" THRU 4.999" W AND LG MAX MASK 4.000" THRU 4.099" MAX WAFER DIA	3670 3262 5540	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	4.000" THRU 4.999" W X 5.000" THRU 5.999" LG MAX MASK 3.500" THRU 3.599" MAX WAFER DIA	3670 3262 5635	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	4.000" THRU 4.999" W X 5.000" THRU 5.999" LG MAX MASK	3670 3262 5640	3670 - AV
ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	4.000" THRU 4.099" MAX WAFER DIA 5.000" THRU 5.999" W AND LG MAX MASK 4.000" THRU 4.099" MAX WAFER DIA	3670 3262 6640	3670 - AV
ALIGNMENT MACHINE, MASK, SEMICONDUCTOR WAFER, AUTOMATIC		3670 3253 0000	3670 - AV
ALIGNMENT MACHINE, MASK, SEMICONDUCTOR WAFER, MANUALLY OPERATED		3670 3251 0000	3670 - AV
ALIGNMENT MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC		3670 3252 0000	3670 - AV
ALIGNMENT MACHINE, SLICE, SEMICONDUCTOR WAFER		3670 3631 0000	3670 - YY
BEADING MACHINE, LEAD WIRE, SEMICONDUCTOR DEVICE		3670 3421 0000	3670 - YY
BEVELING MACHINE, PRINTED CIRCUIT BOARD, AUTOMATIC		3670 1172 0000	3670 - AD
BEVELING MACHINE, PRINTED CIRCUIT BOARD, SEMI-AUTOMATIC		3670 1171 0000	3670 - AD
BONDING MACHINE, BEAM LEAD AND FLIP CHIP, SEMICONDUCTOR DEVICE		3670 3161 0000	3670 - YY
BONDING MACHINE, BEAM LEAD, SEMICONDUCTOR DEVICE, RESISTANCE TYPE		3670 3141 0000	3670 - YY
BONDING MACHINE, BEAM LEAD, SEMICONDUCTOR DEVICE, THERMOCOMPRESSSION TYPE		3670 3142 0000	3670 - YY
BONDING MACHINE, BEAM LEAD, SEMICONDUCTOR DEVICE, ULTRASONIC TYPE		3670 3143 0000	3670 - YY
BONDING MACHINE, DIE, SEMICONDUCTOR DEVICE, EPOXY TYPE		3670 3134 0000	3670 - YY
BONDING MACHINE, DIE, SEMICONDUCTOR DEVICE, RESISTANCE TYPE		3670 3131 0000	3670 - YY
BONDING MACHINE, DIE, SEMICONDUCTOR DEVICE, THERMOCOMPRESSSION TYPE		3670 3132 0000	3670 - YY
BONDING MACHINE, DIE, SEMICONDUCTOR DEVICE, ULTRASONIC TYPE		3670 3133 0000	3670 - YY
BONDING MACHINE, FLIP CHIP, SEMICONDUCTOR DEVICE, RESISTANCE TYPE		3670 3151 0000	3670 - YY

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Description	Size or Capacity	Plant Equipment Code	Descriptive Guide No.
BONDING MACHINE, FLIP CHIP, SEMICONDUCTOR DEVICE, THERMOCOMPRESSSION TYPE		3670 3152 0000	3670-YY
BONDING MACHINE, FLIP CHIP, SEMICONDUCTOR DEVICE, ULTRASONIC TYPE		3670 3153 0000	3670-YY
BONDING MACHINE, SOLDERING AND WELDING, SEMICONDUCTOR DEVICE		3670 3163 0000	3670-YY
BONDING MACHINE, WIRE, DIE AND FLIP CHIP, SEMICONDUCTOR DEVICE		3670 3162 0000	3670-YY
BONDING MACHINE, WIRE, SEMICONDUCTOR DEVICE, RESISTANCE TYPE		3670 3121 0000	3670-YY
BONDING MACHINE, WIRE, SEMICONDUCTOR DEVICE, THERMOCOMPRESSSION		3670 3122 0000	3670-YY
BONDING MACHINE, WIRE, SEMICONDUCTOR DEVICE, THERMOCOMPRESSSION TYPE		3670 3122 0000	3670-YY
BONDING MACHINE, WIRE, SEMICONDUCTOR DEVICE, THERMOCOMPRESSSION-ULTRASONIC TYPE		3670 3125 0000	3670-YY
BONDING MACHINE, WIRE, SEMICONDUCTOR DEVICE, ULTRASONIC TYPE		3670 3122 0000	3670-YY
BONDING MACHINE, WIRE, SEMICONDUCTOR DEVICE, ULTRASONIC TYPE		3670 3123 0000	3670-YY
BONDING MACHINE, WIRE, SEMICONDUCTOR DEVICE, ULTRASONIC TYPE, NUMERICALLY CONTROLLED		3670 3127 0000	3670-YY
BONDING MACHINE, WIRE, SEMICONDUCTOR DEVICE, ULTRASONIC TYPE		3670 3123 0000	3670-YY
BREAKING MACHINE, SEMICONDUCTOR WAFER, AUTOMATIC		3670 3233 0000	3670-AU
BREAKING MACHINE, SEMICONDUCTOR WAFER, MANUALLY OPERATED		3670 3231 0000	3670-AU
BREAKING MACHINE, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC		3670 3232 0000	3670-AU
BREAKING MACHINE, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	5" THRU 5-7/8" MAX CARRIER W AND LG	3670 3232 0505	3670-AU
CLEANING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE		3670 1245 0000	3670-AJ
CLEANING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE	18" THRU 18-7/8" MAX PANEL W	3670 1245 1800	3670-AJ
CLEANING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE	20" THRU 20-7/8" MAX PANEL W	3670 1245 2000	3670-AJ
CLEANING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE	24" THRU 24-7/8" MAX PANEL W	3670 1245 2400	3670-AJ
CLEANING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE		3670 1246 0000	3670-AJ
CLEANING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, SPRAY TYPE	18" THRU 18-7/8" MAX PANEL W	3670 1246 1800	3670-AJ
CLEANING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, SPRAY TYPE	24" THRU 24-7/8" MAX PANEL W	3670 1246 2400	3670-AJ
CLEANING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, SPRAY TYPE		3670 1241 0000	3670-AJ
CLEANING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SIDE, BRUSH TYPE		3670 1242 0000	3670-AJ
CLEANING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SIDE, SPRAY TYPE		3670 1251 0000	3670-AJ
CLEANING COATING AND DRYING MACHINE, PRINTED CIRCUIT BOARD		3670 1235 0000	3670-AJ
CLEANING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE		3670 1235 1800	3670-AJ
CLEANING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE	18" THRU 18-7/8" MAX PANEL W	3670 1235 1800	3670-AJ
CLEANING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE	20" THRU 20-7/8" MAX PANEL W	3670 1235 2000	3670-AJ
CLEANING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE	24" THRU 24-7/8" MAX PANEL	3670 1235 2400	3670-AJ
CLEANING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE	25" THRU 25-7/8" MAX PANEL W	3670 1235 2500	3670-AJ
CLEANING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, SPRAY TYPE		3670 1236 0000	3670-AJ
CLEANING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, SPRAY TYPE	15" THRU 15-7/8" MAX PANEL W	3670 1236 1500	3670-AJ
CLEANING MACHINE PRINTED CIRCUIT BOARD, DOUBLE SIDE, SPRAY TYPE	20" THRU 20-7/8" MAX PANEL W	3670 1236 2000	3670-AJ
CLEANING MACHINE, PRINTED CIRCUIT BOARD, FINGER TYPE		3670 1237 0000	3670-YY
CLEANING MACHINE, PRINTED CIRCUIT BOARD, PLASMA DRY ASHING TYPE		3670 1238 0000	3670-BP

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Description	Size or Capacity	Plant Equipment Code	Descriptive Guide No.
CLEANING MACHINE, PRINTED CIRCUIT BOARD, PLASMA DRY ASHING TYPE	38" THRU 38-7/8" CHAMBER DIA	3670 1238 3848	3670-BP
CLEANING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SIDE, BRUSH TYPE	48" THRU 48-7/8" CHAMBER LG	3670 1231 0000	3670-AJ
CLEANING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SIDE, SPRAY TYPE		3670 1232 0000	3670-AJ
CLEANING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SIDE, SPRAY TYPE	18" THRU 18-7/8" MAX PANEL W	3670 1232 1800	3670-AJ
CLEANING MACHINE, SEMICONDUCTOR WAFER, BRUSH TYPE		3670 3346 0000	3670-BE
CLEANING MACHINE, SEMICONDUCTOR WAFER, BRUSH TYPE	1 SPINDLE 4.000" THRU 4.009" MAX WAFER DIA	3670 3346 1400	3670-BE
CLEANING MACHINE, SEMICONDUCTOR WAFER, BRUSH TYPE	1 SPINDLE 5.000" THRU 5.009" MAX WAFER DIA	3670 3346 1500	3670-BE
CLEANING SYSTEM, PRINTED CIRCUIT BOARD, MODULAR, SPRAY TYPE		3670 1511 0000	3670-AJ
CLEANING SYSTEM, PRINTED CIRCUIT BOARD, MODULAR, SPRAY TYPE	20" THRU 20-7/8" MAX PANEL W	3670 1511 2000	3670-AJ
CLEANING SYSTEM, PRINTED CIRCUIT BOARD, MODULAR, SPRAY TYPE	30" THRU 30-7/8" MAX PANEL W	3670 1511 3000	3670-AJ
COATING AND DEVELOPING MACHINE, SEMICONDUCTOR WAFER, SPINNER TYPE		3670 3291 0000	3670-BE
COATING AND DEVELOPING MACHINE, SEMICONDUCTOR WAFER, SPINNER TYPE	4 SPINDLES 2.850" THRU 2.859" MAX WAFER DIA	3670 3291 4285	3670-BE
COATING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DIP TYPE		3670 1294 0000	3670-AJ
COATING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DIP TYPE	18" THRU 18-7/8" MAX PANEL W	3670 1294 1845	3670-AJ
COATING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DIP TYPE	45" THRU 45-7/8" MAX PANEL LG		
COATING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DIP TYPE	20" THRU 20-7/8" MAX PANEL W	3670 1294 2040	3670-AJ
COATING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, ROLLER TYPE	40" THRU 40-7/8" MAX PANEL LG	3670 1295 0000	3670-AH
COATING MACHINE, PRINTED CIRCUIT BOARD, DIP TYPE		3670 1284 0000	3670-AJ
COATING MACHINE, PRINTED CIRCUIT BOARD, DIP TYPE	10" THRU 10-7/8" MAX PANEL W	36701284 1020	3670-AJ
COATING MACHINE, PRINTED CIRCUIT BOARD, ROLLER TYPE	20" THRU 20-7/8" MAX PANEL LG	3670 1285 0000	3670-AH
COATING MACHINE, PRINTED CIRCUIT BOARD, ROLLER TYPE	9" THRU 9-7/8" MAX PANEL W	3670 1285 0920	3670-AH
COATING MACHINE, PRINTED CIRCUIT BOARD, ROLLER TYPE	.200" THRU .209" MAX PANEL THK		
COATING MACHINE, PRINTED CIRCUIT BOARD, ROLLER TYPE	18" THRU 18-7/8" MAX PANEL W	3670 1285 1825	3670-AH
COATING MACHINE, PRINTED CIRCUIT BOARD, ROLLER TYPE	.250" THRU .259" MAX PANEL THK		
COATING MACHINE, PRINTED CIRCUIT BOARD, ROLLER TYPE	20" THRU 20-7/8" MAX PANEL W	3670 1285 2025	3670-AH
COATING MACHINE, PRINTED CIRCUIT BOARD, ROLLER TYPE	.250" THRU .259" MAX PANEL THK		
COATING MACHINE, PRINTED CIRCUIT BOARD, ROLLER TYPE	24" THRU 24-7/8" MAX PANEL W	3670 1285 2425	3670-AH
COATING MACHINE, PRINTED CIRCUIT BOARD, SPRAY TYPE, AUTOMATIC	.250" THRU .259" MAX PANEL THK	3670 1282 0000	3670-AJ
COATING MACHINE, PRINTED CIRCUIT BOARD, SPRAY TYPE, AUTOMATIC		36701282 1722	3670-AJ
COATING MACHINE, PRINTED CIRCUIT BOARD, SPRAY TYPE, SEMI-AUTOMATIC	17" THRU 17-7/8" MAX PANEL W	3670 1281 0000	3670-AJ
COATING MACHINE, SEMICONDUCTOR WAFER, SPINNER TYPE	22" THRU 22-7/8" MAX PANEL LG	3670 3281 0000	3670-BE
COATING MACHINE, SEMICONDUCTOR WAFER, SPINNER TYPE	1 SPINDLE 4.850" THRU 4.859" MAX WAFER DIA	3670 3281 1485	3670-BE
COATING MACHINE, SEMICONDUCTOR, VAPOR CHAMBER TYPE		3670 3283 0000	3670-YY
CONTROL AND CALIBRATE UNIT, MICRORESISTOR TRIMMING MACHINE		3670 3371 0000	3670-YY
CUTTING MACHINE, PROFILE, POTENTIOMETER CARD		3670 2131 0000	3670-YY
DEBONDER, DIE, SEMICONDUCTOR DEVICE, HOT GAS TYPE		3670 3921 0000	3670-YY
DEBURRING RINSING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE		3670 1255 0000	3670-AH
DEBURRING RINSING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE	20" THRU 20-7/8" MAX PANEL W	3670 1255 2025	3670-AH
DETECTOR, LOOSE PARTICLE, ELECTRONIC COMPONENT	.250" THRU .259" MAX PANEL THK	3670 3527 0000	3670-YY
DEVELOPER-RINSER, DRYER, PHOTO RESIST, PRINTED CIRCUIT BOARD, HORIZONTAL CONVEYOR TYPE	24" THRU 24-7/8" MAX PANEL W	3670 1336 2425	3670-AH
	.250" THRU .259" MAX PANEL THK		

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Description	Size or Capacity	Plant Equipment Code	Descriptive Guide No.
DEVELOPER-RINSER, DRYER, PHOTO RESIST, PRINTED CIRCUIT BOARD, VERTICAL CONVEYOR TYPE	18" THRU 18-7/8" MAX PANEL W 45" THRU 45-7/8" MAX PANEL LG	3670 1335 1845	3670-AH
DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, CONVEYOR TYPE		3670 1332 0000	3670-AJ
DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, HORIZONTAL CONVEYOR TYPE	15" THRU 15-7/8" MAX PANEL W .250" THRU .259" MAX PANEL THK	3670 1334 1525	3670-AH
DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, HORIZONTAL CONVEYOR TYPE	20" THRU 20-7/8" MAX PANEL W .370" THRU .379" MAX PANEL THK	3670 1334 2037	3670-AH
DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, HORIZONTAL CONVEYOR TYPE	24" THRU 24-7/8" MAX PANEL W .370" THRU .379" MAX PANEL THK	3670 1334 2437	3670-AH
DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, MANUAL LOAD		3670 1331 0000	3670-AJ
DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, MANUAL LOAD	21" THRU 21-7/8" MAX PANEL W 26" THRU 267/8" MAX PANEL LG	3670 1331 2126	3670-AJ
DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, MANUAL LOAD	24" THRU 24-7/8" MAX PANEL W 26" THRU 26-7/8" MAX PANEL LG	3670 1331 2426	3670-AJ
DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, MANUAL LOAD	24" THRU 24-7/8" MAX PANEL W 48" THRU 48-7/8" MAX PANEL LG	3670 1331 2448	3670-AJ
DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, MANUAL LOAD	30" THRU 30-7/8" MAX PANEL W 24" THRU 24-7/8" MAX PANEL LG	3670 1331 3024	3670-AJ
DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, ULTRASONIC, MANUAL LOAD		3670 1333 0000	3670-AJ
DEVELOPER, PHOTO RESIST, SEMICONDUCTOR WAFER, SPINNER TYPE		3670 3333 0000	3670-BE
DEVELOPER, PHOTO RESIST, SEMICONDUCTOR WAFER, SPINNER TYPE	1 SPINDLE 5.000" THRU 5.009" MAX WAFER DIA	3670 3333 1500	3670-BE
DEVELOPER, PHOTO RESIST, SEMICONDUCTOR WAFER, SPRAY TYPE		3670 3331 0000	3670-BF
DEVELOPER, PHOTO RESIST, SEMICONDUCTOR WAFER, SPRAY TYPE	10 MAX WAFERS .000" THRU .999" MIN WAFER DIA 2.000" THRU 2.999" MAX WAFER DIA	3670 3331 1013	3670-BF
DOPING SYSTEM, VACUUM, ION IMPLANTATION DRILLING AND PINNING MACHINE, PRINTED CIRCUIT BOARD		3670 3455 0000 3670 1160 0000	3670-W 3670-YY
*DRILLING AND PINNING MACHINE, PRINTED CIRCUIT BOARD, AUTOMATIC		3670 1162 0000	3670-YY
DRILLING AND PINNING MACHINE, PRINTED CIRCUIT BOARD, AUTOMATIC	.026 - .050" MIN & .201 - .250" MAX DRILL DIA 21 - 24-7/8" W X 31 - 36-7/8" LG MAX BOARD	3670 1162 3868	3670-YY
*DRILLING AND PINNING MACHINE, PRINTED CIRCUIT BOARD, SEMI-AUTOMATIC		3670 1161 0000	3670-YY
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI SPINDLE, NUMERICALLY CONTROLLED	.011 - .025" MIN & .076 - .100" MAX DRILL DIA 17 - 20-7/8" W & LG MAX BOARD	3670 1123 2555	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI SPINDLE, NUMERICALLY CONTROLLED	.026 - .050" MIN & .151 - .200" MAX DRILL CAP. 9 - 12-7/8" W X 17 - 20-7/8" LG MAX BOARD	3670 1123 3735	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, AUTOMATIC		3670 1122 0000	3670-AB
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED		3670 1123 0000	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	0 - .010" MIN & .101 - .150" MAX DRILL DIA 9 - 12-7/8" W X 13 - 16-7/8" LG MAX BOARD	3670 1123 1634	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	0 - .010" MIN & .101 - .150" MAX DRILL DIA 9 - 12-7/8" W X 17 - 20-7/8" LG MAX BOARD	3670 1123 1635	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	0 - .010" MIN & .151 - .200" MAX DRILL DIA 9 - 12-7/8" W X 13 - 16-7/8" LG MAX BOARD	3670 1123 1734	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	0 - .010" MIN & .201 - .250" MAX DRILL DIA 25-30-7/8" W X 37" & ABOVE LG MAX BOARD	3670 1123 1879	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	.011 - .025" MIN & .101 - .150" MAX DRILL DIA 9 - 12-7/8" W X 17 - 20-7/8" LG MAX BOARD	3670 1123 2635	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	.011"-.025" MIN & 151"-200" MAX DRILL DIA	3670 1123 2700	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	.011" - .025" MIN & .151 - .200" MAX DRILL DIA 9 - 12-7/8" W X 21 - 24-7/8" LG MAX BOARD	3670 1123 2736	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	.011 - .025" MIN & .201 - .250" MAX DRILL DIA 9 - 12-7/8" W X 13 - 16-7/8" LG MAX BOARD	3670 1123 2834	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	.011 - .025" MIN & .201 - .250" MAX DRILL DIA 13 - 16-7/8" W X 17 - 20-7/8" LG MAX BOARD	3670 1123 2845	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	.011 - .025" MIN & .201 - .250" MAX DRILL DIA 13 - 16-7/8" W X 21 - 24-7/8" LG MAX BOARD	3670 1123 2846	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	.011 - .025" MIN & .201 - .250" MAX DRILL DIA 21 - 24-7/8" W & LG MAX BOARD	3670 1123 2866	3670-AC

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DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	011- .025" MIN & .201- .250" MAX DRILL DIA 25 - 30-7/8" W & LG MAX BOARD	3670 1123 2877	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	026 -.050" MIN & .201 - .250" MAX DRILL DIA 13 - 16-7/8" W X 37" & ABOVE LG MAX BOARD	3670 1123 3849	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	051-.075" MIN & .201-.250" MAX DRILL DIA 25-30-7/8" W X 37" & ABOVE LG MAX BOARD	3670 1123 4879	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, SEMI-AUTOMATIC		3670 1121 0000	3670-AB
DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, AUTOMATIC		3670 1112 0000	3670-AB
DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, NUMERICALLY CONTROLLED		3670 1113 0000	3670-AC
DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, SEMI-AUTOMATIC		3670 1111 0000	3670-AA
DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, SEMI-AUTOMATIC	0 - .010" MIN & .101 -.150" MAX DRILL DIA 13 - 13-7/8" THROAT D	3670 1111 1613	3670-AA
DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, SEMI-AUTOMATIC	0 - .010" MIN & .201 - .250" MAX DRILL DIA 12 - 12-7/8" THROAT D	3670 1111 1812	3670-AA
DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, SEMI-AUTOMATIC	011- .025" MIN & .101 - .150" MAX DRILL DIA 12 -12-7/8" THROAT D	3670 1111 2612	3670-AA
DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, SEMI-AUTOMATIC	011- .025" MIN & .151 - .200" MAX DRILL DIA 12 - 12-7/8" THROAT D	3670 1111 2712	3670-AA
DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, SEMI-AUTOMATIC	011- .025" MIN & .201 - .250" MAX DRILL DIA 10 - 10-7/8" THROAT D	3670 1111 2810	3670-AA
DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, SEMI-AUTOMATIC	026 - .050" MIN & .151 - .200" MAX DRILL DIA 15 - 15-7/8" THROAT D	3670 1111 3715	3670-AA
DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	026 -.050" MIN & .151 - 200" MAX DRILL DIA 17 - 20-7/8" W X LG MAX BOARD	3670 1123 2855	3670-AC
DRYING MACHINE, PRINTED CIRCUIT BOARD, HORIZONTAL CONVEYOR TYPE		3670 1272 0000	3670-AJ
DRYING MACHINE, PRINTED CIRCUIT BOARD, HORIZONTAL CONVEYOR TYPE	8" THRU 8-7/8" MAX PANEL W	3670 1272 0800	3670-AJ
DRYING MACHINE, PRINTED CIRCUIT BOARD, HORIZONTAL CONVEYOR TYPE	24" THRU 24-7/8" MAX PANEL W	3670 1272 2400	3670-AJ
DRYING MACHINE, PRINTED CIRCUIT BOARD, HORIZONTAL CONVEYOR TYPE	30" THRU 30-7/8" MAX PANEL W	3670 1272 3000	3670-AJ
DRYING MACHINE, PRINTED CIRCUIT BOARD, OVEN TYPE		3670 1274 0000	3670-AJ
DRYING MACHINE, PRINTED CIRCUIT BOARD, OVEN TYPE	22" THRU 22-7/8" MAX PANEL W 24" THRU 24-7/8" MAX PANEL LG	3670 1274 2224	3670-AJ
DRYING MACHINE, PRINTED CIRCUIT BOARD, ROLLER TYPE		3670 1271 0000	3670-AH
DRYING MACHINE, PRINTED CIRCUIT BOARD, VERTICAL CONVEYOR TYPE		3670 1273 0000	3670-AJ
DRYING MACHINE, PRINTED CIRCUIT BOARD, VERTICAL CONVEYOR TYPE	24" THRU 24-7/8" MAX PANEL W AND LG	3670 1273 2424	3670-AJ
DRYING SYSTEM, SOLVENT, SEMICONDUCTOR WAFER		3670 3411 0000	3670-BL
ENGRAVER, PRINTED CIRCUIT BOARD, SCANNING-CUTTING TYPE, DOUBLE HEAD		3670 1352 0000	3670-AM
ENGRAVER, PRINTED CIRCUIT BOARD, SCANNING-CUTTING TYPE, SINGLE HEAD		3670 1351 0000	3670-AM
ENGRAVER, PRINTED CIRCUIT BOARD, SCANNING-CUTTING TYPE, SINGLE HEAD	10" THRU 10-7/8" MAX PANEL W 12" THRU 12-7/8" MAX PANEL LG	3670 1351 1012	3670-AM
ENGRAVER, PRINTED CIRCUIT BOARD, SCANNING-CUTTING TYPE, SINGLE HEAD	12" THRU 12-7/8" MAX PANEL W 18" THRU 18-7/8" MAX PANEL LG	3670 1351 1218	3670-AM
ETCHING MACHINE, ION BEAM, SEMICONDUCTOR WAFER		3670 3355 0000	3670-YY
ETCHING MACHINE, SPRAY, SEMICONDUCTOR WAFER, ROTARY WORKHOLDER TYPE		3670 3351 0000	3670-BF
EXHAUST AND BACK FILLING MACHINE, SEMICONDUCTOR DEVICE		3670 3393 0000	3670-YY
EXPANDER, DIE MATRIX, SEMICONDUCTOR WAFER		3670 3931 0000	3670-YY
EXPOSURE UNIT, METALLIZED SUBSTRATE, REDUCTION CAMERA TYPE		3670 3321 0000	3670-BK
EXPOSURE UNIT, METALLIZED SUBSTRATE, REDUCTION CAMERA TYPE	1.000" THRU 1.099" W AND LG MAX SUBSTRATE	3670 3321 1010	3670-BK
EXPOSURE UNIT, METALLIZED SUBSTRATE, REDUCTION CAMERA TYPE	5" W X 5" LG MAX SUBSTRATE	3670 3321 5050	3670-BK
EXPOSURE UNIT, PHOTO MASK, FRAME TYPE	4.000" THRU 4.099" W X 5.000" THRU 5.099" LG MAX MASK	3670 3323 4050	3670-BK
EXPOSURE UNIT, PHOTO RESIST, COLLIMATED ULTRAVIOLET LIGHT		3670 3325 0000	3670-BM

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EXPOSURE UNIT, PHOTO RESIST, COLLIMATED ULTRAVIOLET LIGHT	4" THRU 4-7/8" DIA BEAM 200 THRU 209 WATT LAMP	3670 3325 4020	3670-BM
EXPOSURE UNIT, PHOTO RESIST, COLLIMATED ULTRAVIOLET LIGHT	6" THRU 6-7/8" DIA BEAM 200 THRU 209 WATT LAMP	3670 3325 6020	3670-BM
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, CONVEYOR TYPE		3670 1326 0000	3670-AK
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE		3670 1325 0000	3670-AK
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	20" THRU 20-7/8" MAX PANEL W	3670 1325 2024	3670-AK
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	24" THRU 24-7/8" MAX PANEL LG	3670 1325 2425	3670-AK
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	25" THRU 25-7/8" MAX PANEL LG.	3670 1325 2448	3670-AK
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	24" THRU 24-7/8" MAX PANEL W	3670 1325 2448	3670-AK
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	48" THRU 48-7/8" MAX PANEL LG	3670 1325 3040	3670-AK
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	30" THRU 30-7/8" MAX PANEL W	3670 1325 3072	3670-AK
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	40" THRU 40-7/8" MAX PANEL LG	3670 1325 3072	3670-AK
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	30" THRU 30-7/8" MAX PANEL W	3670 1325 3648	3670-AK
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	72" THRU 72-7/8" MAX PANEL LG	3670 1325 3648	3670-AK
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	36" THRU 36-7/8" MAX PANEL W	3670 1321 0000	3670-AK
EXPOSURE UNIT, PRINTED CIRCUIT BOARD, SINGLE SIDE, FRAME TYPE	48" THRU 48-7/8" MAX PANEL LG	3670 2127 0000	3670-YY
FORMING AND TRIMMING MACHINE, AXIAL AND RADIAL LEAD		3670 2112 0000	3670-YY
FORMING AND TRIMMING MACHINE, AXIAL LEAD		3670 2124 0000	3670-YY
FORMING AND TRIMMING MACHINE, LEAD, DIP		3670 2125 0000	3670-YY
FORMING AND TRIMMING MACHINE, LEAD, FLAT PACK		3670 2122 0000	3670-YY
FORMING AND TRIMMING MACHINE, RADIAL LEAD		3670 2111 0000	3670-YY
FORMING MACHINE, AXIAL LEAD		3670 1392 0000	3670-AP
FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, DOUBLE SIDE			
FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, DOUBLE SIDE	3" THRU 3-7/8" MAX PANEL W	3670 1392 0300	3670-AP
FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, DOUBLE SIDE	10" THRU 10-7/8" MAX PANEL W	3670 1392 1000	3670-AP
FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, DOUBLE SIDE	15" THRU 15-7/8" MAX PANEL W	3670 1392 1100	3670-AP
FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, DOUBLE SIDE	20" THRU 20-7/8" MAX PANEL W	3670 1392 2000	3670-AP
FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, DOUBLE SIDE	24" THRU 24-7/8" MAX PANEL W	3670 1392 2400	3670-AP
FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, SINGLE SIDE		3670 1391 0000	3670-AP
FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, TRAY TYPE, DOUBLE SIDE		3670 1396 0000	3670-AJ
FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, TRAY TYPE, DOUBLE SIDE	15" THRU 15-7/8" MAX PANEL W	3670 1396 1512	3670-AJ
FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, TRAY TYPE, DOUBLE SIDE	12" THRU 12-7/8" MAX PANEL LG	3670 3551 0000	3670-YY
GOLD SPIKING SYSTEM, INFRARED, SEMICONDUCTOR WAFER		3670 2151 0000	3670-YY
GRINDING MACHINE, RESISTOR, HELIX SPIRALING		3670 3524 0000	3670-YY
GROOVING MACHINE, SEMICONDUCTOR WAFER, DIFFUSED LAYER MEASUREMENT		3670 1423 0000	3670-AR
INSPECTION MACHINE, PRINTED CIRCUIT BOARD, OPTICAL COMPARATOR TYPE			
INSPECTION MACHINE, PRINTED CIRCUIT BOARD, OPTICAL COMPARATOR TYPE	12" THRU 12-7/8" MAX PANEL W AND LG	3670 1423 1212	3670-AR
INSPECTION MACHINE, SEMICONDUCTOR WAFER, DIE-TO-DIE STEPPING		3670 3528 0000	3670-YY
LAMINATOR, FILM RESIST, ROLLER TYPE, HEATED		3670 1311 0000	3670-AH
LAMINATOR, FILM RESIST, ROLLER TYPE, HEATED	18" THRU 18-7/8" MAX PANEL W	3670 1311 1825	3670-AH
LAMINATOR, FILM RESIST, ROLLER TYPE, HEATED	.250" THRU .259" MAX PANEL THK		
LAMINATOR, FILM RESIST, ROLLER TYPE, HEATED	25" THRU 25-7/8" MAX PANEL W	3670 1311 2537	3670-AH
LAMINATOR, FILM RESIST, ROLLER TYPE, HEATED	.370" THRU .379" MAX PANEL THK		
LAMINATOR, FILM RESIST, ROLLER TYPE, HEATED	26" THRU 26-7/8" MAX PANEL W	3670 1311 2625	3670-AH
LAMINATOR, FILM RESIST, ROLLER TYPE, HEATED	.250" THRU .259" MAX PANEL THK		
LAYOUT AND DRILLING MACHINE, PRINTED CIRCUIT BOARD, AUTOMATIC		3670 1152 0000	3670-AB
LAYOUT AND DRILLING MACHINE, PRINTED CIRCUIT BOARD, NUMERICALLY CONTROLLED		3670 1153 0000	3670-AC
LAYOUT AND DRILLING MACHINE, PRINTED CIRCUIT BOARD, NUMERICALLY CONTROLLED	011 - .025" MIN & .201 - .250" MAX DRILL DIA 17 - 20-7/8" W & LG MAX BOARD	3670 1153 2855	3670-AC

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LAYOUT AND DRILLING MACHINE, PRINTED CIRCUIT BOARD, SEMI-AUTOMATIC		3670 1151 0000	3670-AB
LAYOUT AND DRILLING MACHINE, PRINTED CIRCUIT BOARD, SEMI-AUTOMATIC	0 - .010" MIN & .151 - .200" MAX DRILL DIA	3670 1151 1756	3670-AB
LAYOUT AND DRILLING MACHINE, PRINTED CIRCUIT BOARD, SEMI-AUTOMATIC	17 - 20-7/8" W X 21 - 24-7/8" LG MAX BOARD	3670 1151 2723	3670-AB
LAYOUT AND DRILLING MACHINE, PRINTED CIRCUIT BOARD, SEMI-AUTOMATIC	011 -.025" MIN & .151 - .200" MAX DRILL DIA		
LAYOUT MACHINE, PRINTED CIRCUIT BOARD, SEMI-AUTOMATIC	5 - 8-7/8" W X 9 - 12-7/8" LG MAX BOARD	3670 1145 0000	3670-AN
LEVELING MACHINE, SOLDER, PRINTED CIRCUIT BOARD, CONVEYOR TYPE		3670 1382 0000	3670-AP
LEVELING MACHINE, SOLDER, PRINTED CIRCUIT BOARD, FRAME TYPE		3670 1381 0000	3670-AP
LEVELING MACHINE, SOLDER, PRINTED CIRCUIT BOARD, FRAME TYPE	18" THRU 18-7/8" MAX PANEL W	3670 1381 1824	3670-AP
LEVELING MACHINE, SOLDER, PRINTED CIRCUIT BOARD, FRAME TYPE	24" THRU 24-7/8" MAX PANEL LG		
LEVELING MACHINE, SOLDER, PRINTED CIRCUIT BOARD, FRAME TYPE	24" THRU 24-7/8" MAX PANEL W	3670 1381 2440	3670-AP
LEVELING MACHINE, SOLDER, PRINTED CIRCUIT BOARD, FRAME TYPE	40" THRU 40-7/8" MAX PANEL LG		
LEVELING MACHINE, SOLDER, PRINTED CIRCUIT BOARD, FRAME TYPE	24" THRU 24-7/8" MAX PANEL W	3670 1381 2444	3670-AP
LEVELING MACHINE, SOLDER, PRINTED CIRCUIT BOARD, FRAME TYPE	44" THRU 44-7/8" MAX PANEL LG		
LOADING AND ORIENTATING MACHINE, SEMICONDUCTOR SUBSTRATE		3670 3621 0000	3670-YY
LOADING MACHINE, SEMICONDUCTOR SUBSTRATE		3670 3611 0000	3670-YY
MEASURING SYSTEM, PHOTOMASK, SEMICONDUCTOR WAFER		3670 3521 0000	3670-YY
MONITOR, WIRE BOND, RECORDER		3670 3525 0000	3670-YY
NOTCHING MACHINE, PRINTED CIRCUIT BOARD, AUTOMATIC		3670 1182 0000	3670-AD
NOTCHING MACHINE, PRINTED CIRCUIT BOARD, SEMI-AUTOMATIC		3670 1181 0000	3670-AD
PATTERN GENERATOR, PHOTOMASK, SEMICONDUCTOR WAFER, NUMERICALLY CONTROLLED		3670 3533 0000	3670-YY
PHOTOMASK MACHINE, STEP AND REPEAT, AUTOMATIC POSITIONING		3670 3513 0000	3670-BG
PHOTOMASK MACHINE, STEP AND REPEAT, MANUAL POSITIONING		3670 3511 0000	3670-BG
PHOTOMASK MACHINE, STEP AND REPEAT, SEMI-AUTOMATIC POSITIONING		3670 3512 0000	3670-BG
PHOTOMASK MACHINE, STEP AND REPEAT, SEMI-AUTOMATIC POSITIONING	2" THRU 2-7/8" MAX MASK W AND LG	3670 3512 0202	3670-BG
PHOTOMASK MACHINE, STEP AND REPEAT, SEMI-AUTOMATIC POSITIONING	3" THRU 3-7/8" MAX MASK W AND LG	3670 3512 0303	3670-BG
PHOTOMASK MACHINE, STEP AND REPEAT, SEMI-AUTOMATIC POSITIONING	5" THRU 5-7/8" MAX MASK W AND LG	3670 3512 0505	3670-BG
PHOTOMASK SYSTEM, PHOTO REPEATER AND PATTERN GENERATOR, NUMERICALLY CONTROLLED		3670 3517 0000	3670-YY
POLISHING MACHINE, PRINTED CIRCUIT BOARD, DRUM TYPE		3670 1221 0000	3670-AG
POLISHING MACHINE, PRINTED CIRCUIT BOARD, DRUM TYPE	15" THRU 15-7/8" MAX PANEL W	3670 1221 1510	3670-AG
POLISHING MACHINE, PRINTED CIRCUIT BOARD, DRUM TYPE	1.000" THRU 1.099" MAX PANEL THK		
POLISHING MACHINE, PRINTED CIRCUIT BOARD, DRUM TYPE	18" THRU 18-7/8" MAX PANEL W	3670 1221 1830	3670-AG
POLISHING MACHINE, PRINTED CIRCUIT BOARD, DRUM TYPE	3.000" THRU 3.099" MAX PANEL THK		
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE	3" THRU 3-7/8" MAX PRINT W	3670 1342 0304	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE	4" THRU 4-7/8" MAX PRINT LG		
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE	12" THRU 12-7/8" MAX PRINT W	3670 1343 1212	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE	12" THRU 12-7/8" MAX PRINT LG		
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, AUTOMATIC		3670 1343 0000	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, AUTOMATIC	3" THRU 3-7/8" MAX PRINT W AND LG	3670 1343 0303	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, AUTOMATIC	4" THRU 4-7/8" MAX PRINT W	3670 1343 0405	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, AUTOMATIC	5" THRU 5-7/8" MAX PRINT LG		
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, AUTOMATIC	8" THRU 8-7/8" MAX PRINT W AND LG	3670 1343 0808	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, MANUALLY OPERATED		3670 1341 0000	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, MANUALLY OPERATED	17" THRU 17-7/8" MAX PRINT W	3670 1341 1729	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, MANUALLY OPERATED	29" THRU 29-7/8" MAX PRINT LG		
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC		3670 1342 0000	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	2" THRU 2-7/8" MAX PRINT W AND LG	3670 1342 0202	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	3" THRU 3-7/8" MAX PRINT W AND LG	3670 1342 0303	3670-AL

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PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	4" THRU 4-7/8" MAX PRINT W	36701342 0406	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	6" THRU 6-7/8" MAX PRINT LG	3670 1342 0505	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	5" THRU 5-7/8" MAX PRINT W AND LG	3670 1342 0606	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	6" THRU 6-7/8" MAX PRINT W AND LG	3670 1342 0810	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	8" THRU 8-7/8" MAX PRINT W	3670 1342 1212	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	10" THRU 10-7/8" MAX PRINT LG	3670 1342 1218	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	12" THRU 12-7/8" MAX PRINT W	3670 1342 1422	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	18" THRU 18-7/8" MAX PRINT LG	3670 1342 2538	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	14" THRU 14-7/8" MAX PRINT W	3670 1343 0810	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	22" THRU 22-7/8" MAX PRINT LG	3670 3313 0000	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	25" THRU 25-7/8" MAX PRINT W	3670 3311 0000	3670-AL
PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	38" THRU 38-7/8" MAX PRINT LG	3670 3312 0000	3670-AL
PRINTER, SEMICONDUCTOR WAFER, SCREEN TYPE, AUTOMATIC	8" THRU 8-7/8" MAX PRINT W	3670 1515 0000	3670-AL
PRINTER, SEMICONDUCTOR WAFER, SCREEN TYPE, MANUALLY OPERATED	10" THRU 10-7/8" MAX PRINT LG	3670 1515 1524	3670-AL
PRINTER, SEMICONDUCTOR WAFER, SCREEN TYPE, SEMI-AUTOMATIC	15" THRU 15-7/8" MAX PRINT W	3670 3113 0000	3670-AL
*PRINTING SYSTEM, PRINTED CIRCUIT BOARD, SCREEN TYPE	24" THRU 24-7/8" MAX PRINT LG	3670 3113 1833	3670-AL
PRINTING SYSTEM, PRINTED CIRCUIT BOARD, SCREEN TYPE	18 MAX PROBE HDS	3670 3113 2033	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC	2.000" THRU 2.999" X AND Y AXIS TVL	3670 3113 2433	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC	20 MAX PROBE HDS	3670 3113 2455	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC	2.000" THRU 2.999" X AND Y AXIS TVL	3670 3113 6055	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC	24 MAX PROBE HDS	3670 3111 0000	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC	2.000" THRU 2.999" X AND Y AXIS TVL	3670 3111 0333	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC	4.000" THRU 4.999" X AND Y AXIS TVL	3670 3111 0677	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC	60 MAX PROBE HDS	3670 3111 0832	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC	4.000" THRU 4.999" X AND Y AXIS	3670 3111 0833	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	3 MAX PROBE HDS	3670 3111 0844	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	2.000" THRU 2.999" X AND Y AXIS TVL	3670 3111 0855	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	6 MAX PROBE HDS	3670 3111 0933	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	6.000" THRU 6.999" X AND Y AXIS TVL	3670 3111 1022	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	8 MAX PROBE HDS	3670 3111 1255	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	1.000" THRU 1.999" Y AXIS TVL	3670 3111 1400	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	8 MAX PROBE HDS	3670 3111 1833	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	2.000" THRU 2.999" X AND Y AXIS TVL	3670 3111 2022	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	8 MAX PROBE HDS	3670 3111 2044	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	3.000" THRU 3.999" X AND Y AXIS TVL	3670 3111 2444	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	4.000" THRU 4.999" X AND Y AXIS TVL	3670 3111 7011	3670-AL
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	9 MAX PROBE HDS		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	2.000" THRU 2.999" X AND Y TVL		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	10 MAX PROBE HDS		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	1.000" THRU 1.999" X AND Y AXIS TVL		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	12 MAX PROBE HDS		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	4.000" THRU 4.999" X AND Y AXIS TVL		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	14 MAX PROBE HDS		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	18 MAX PROBE HDS		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	2.000" THRU 2.999" X AND Y AXIS TVL		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	20 MAX PROBE HDS		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	1.000" THRU 1.999" X AND Y AXIS TVL		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	20 MAX PROBE HDS		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	3.000" THRU 3.999" X AND Y AXIS TVL		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	24 MAX PROBE HDS		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	3.000" THRU 3.999" X AND Y AXIS TVL		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	70 MAX PROBE HDS		
PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	000" THRU .999" X AND Y AXIS TVL		

Section 1-NOMENCLATURE TO PEC

Description	Size or Capacity	Plant Equipment Code	Descriptive Guide No.
PROBING MACHINE, SEMICONDUCTOR DEVICE, SEMI-AUTOMATIC		3670 3112 0000	3670-BC
PROBING MACHINE, SEMICONDUCTOR DEVICE, SEMI-AUTOMATIC	18 MAX PROBE HDS	3670 3112 1822	3670-BC
PROBING MACHINE, SEMICONDUCTOR DEVICE, SEMI-AUTOMATIC	1.000" THRU 1.999" X AND Y AXIS TVL	3670 3112 2022	3670-BC
PROBING MACHINE, SEMICONDUCTOR DEVICE, SEMI-AUTOMATIC	20 MAX PROBE HDS		
PROBING MACHINE, SEMICONDUCTOR DEVICE, SEMI-AUTOMATIC	1.000" THRU 1.999" X AND Y AXIS TVL	3670 3114 0000	3670-YY
PROBING STATION, SEMICONDUCTOR DEVICE, FIXED PATTERN TYPE		3670 3115 0000	3670-YY
PROBING SYSTEM, SEMICONDUCTOR DEVICE, FIXED PATTERN TYPE			
PROCESSING MACHINE, PRINTED CIRCUIT BOARD, MULTI-OPERATION		3670 1371 0000	3670-AN
PROCESSING MACHINE, PRINTED CIRCUIT BOARD, MULTI-OPERATION	5" THRU 5-7/8" MAX PANEL W AND LG	3670 1371 0505	3670-AN
PROCESSING MACHINE, PRINTED CIRCUIT BOARD, MULTI-OPERATION	12" THRU 12-7/8" MAX PANEL W AND LG	3670 1371 1212	3670-AN
PROCESSING MACHINE, PRINTED CIRCUIT BOARD, MULTI-OPERATION		3670 3915 0000	3670-YY
PROCESSING UNIT, SEMICONDUCTOR WAFER, MULTI-OPERATION		3670 1142 0000	3670-BB
PUNCHING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, AUTOMATIC		3670 1143 0000	3670-AF
PUNCHING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED		3670 1141 0000	3670-BB
PUNCHING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, SEMI-AUTOMATIC			
PUNCHING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, SEMI-AUTOMATIC	151 - .200" MIN & .201 - .250" MAX PUNCH DIA	3670 1141 7867	3670-BB
PUNCHING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, SEMI-AUTOMATIC	21 - 24-7/8" W X 25 - 30-7/8" LG MAX BOARD	3670 1132 0000	3670-BB
PUNCHING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, AUTOMATIC		3670 1133 0000	3670-AF
PUNCHING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, NUMERICALLY CONTROLLED		3670 1131 0000	3670-BA
PUNCHING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, SEMI-AUTOMATIC		3670 3442 0000	3670-BH
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, DUAL CHAMBER		3670 3442 0815	3670-BH
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, DUAL CHAMBER	8 MAX WAFERS		
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, DUAL CHAMBER	1.500" THRU 1.5999" MAX WAFER DIA	3670 3442 2412	3670-BH
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, DUAL CHAMBER	24 MAX WAFERS		
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, DUAL CHAMBER	1.200" THRU 1.299" MAX WAFER DIA	3670 3441 0000	3670-BH
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER		3670 3441 0410	3670-AH
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	4 MAX WAFERS		
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	1.000" THRU 1.099" MAX WAFER DIA	3670 3441 0420	3670-BH
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	7 MAX WAFERS		
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	2.000" THRU 2.099" MAX WAFER DIA	3670 3441 0430	3670-BH
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	4 MAX WAFERS		
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	3.000" THRU 3.099" MAX WAFER DIA	3670 3441 1421	3670-BH
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	14 MAX WAFERS		
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	2.100" THRU 2.199" MAX WAFER DIA	3670 3441 1812	3670-BH
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	18 MAX WAFERS		
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	1.200" THRU 1.299" MAX WAFER DIA	3670 3441 1820	3670-BH
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	18 MAX WAFERS		
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	2.000" THRU 2.099" MAX WAFER DIA	3670 3441 2030	3670-BH
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	20 MAX WAFERS		
REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, SINGLE CHAMBER	3.000" THRU 3.099" MAX WAFER DIA	3670 3453 0000	3670-BH
*REACTOR, ETCHING, PLASMA, SEMICONDUCTOR WAFER, SINGLE CHAMBER		3670 3461 0000	3670-BH
*REACTOR, SILICON NITRIDE, SEMICONDUCTOR WAFER, SINGLE CHAMBER			
REACTOR, SILICON NITRIDE, SEMICONDUCTOR WAFER, SINGLE CHAMBER	1 MAX WAFER	3670 3461 0140	3670-BH
REACTOR, SILICON NITRIDE, SEMICONDUCTOR WAFER, SINGLE CHAMBER	4.000" THRU 4.099" MAX WAFER DIA	3670 3452 0000	3670-BH
REACTOR, SILICON OXIDE, SEMICONDUCTOR WAFER, BATCH TYPE			
REACTOR, SILICON OXIDE, SEMICONDUCTOR WAFER, BATCH TYPE	18 MAX WAFERS	3670 3452 1820	3670-BH
REACTOR, SILICON OXIDE, SEMICONDUCTOR WAFER, BATCH TYPE	2.000" THRU 2.099" MAX WAFER DIA	3670 3451 0000	3670-BH
REACTOR, SILICON OXIDE, SEMICONDUCTOR WAFER, ROTATING CARRIER			
REACTOR, SILICON OXIDE, SEMICONDUCTOR WAFER, ROTATING CARRIER	7 MAX WAFERS	3670 3451 0720	3670-BH
REACTOR, SILICON OXIDE, SEMICONDUCTOR WAFER, ROTATING CARRIER	2.000" THRU 2.099" MAX WAFER DIA		
REPAIR AND ASSEMBLY STATION, PROBE CARD		3670 3129 0000	3670-YY
RINSER-DRYER, SEMICONDUCTOR WAFER, SPRAY TYPE		3670 3345 0000	3670-YY
RINSER-DRYER, SEMICONDUCTOR WAFER, SPRAY TYPE			
RINSER-DRYER, SEMICONDUCTOR WAFER, SPRAY TYPE	1 WAFER CARRIER	3670 3345 1500	3670-BN
RINSER-DRYER, SEMICONDUCTOR WAFER, SPRAY TYPE	5.000" THRU 5.009" MAX WAFER DIA		

Section 1-NOMENCLATURE TO PEC

Description	Size or Capacity	Plant Equipment Code	Descriptive Guide No.
RINSER-DRYER, SEMICONDUCTOR WAFER, SPRAY TYPE	2 MAX WAFER CARRIERS 3.000" THRU 3.009" MAX WAFER DIA	3670 3345 2300	3670-BN
RINSER-DRYER, SEMICONDUCTOR WAFER, SPRAY TYPE	4 MAX WAFER CARRIERS 4.000" THRU 4.009" MAX WAFER DIA	3670 3345 4400	3670-BN
SAWING MACHINE, PRINTED CIRCUIT BOARD, AUTOMATIC		3670 1192 0000	3670-AD
SAWING MACHINE, PRINTED CIRCUIT BOARD, SEMI-AUTOMATIC		3670 1191 0000	3670-AD
SCRIBING MACHINE, SEMICONDUCTOR WAFER, DIAMOND TOOL TYPE, AUTOMATIC		3670 3223 0000	3670-AT
SCRIBING MACHINE, SEMICONDUCTOR WAFER, DIAMOND TOOL TYPE, AUTOMATIC	1 SCRIBING HD 1.500" THRU 1.509" MAX WAFER DIA	3670 3223 1150	3670-AT
SCRIBING MACHINE, SEMICONDUCTOR WAFER, DIAMOND TOOL TYPE, AUTOMATIC	1 SCRIBING HD 2.000" THRU 2.009" MAX WAFER DIA	3670 3223 1200	3670-AT
SCRIBING MACHINE, SEMICONDUCTOR WAFER, DIAMOND TOOL TYPE, AUTOMATIC	1 SCRIBING HD 3.000" THRU 3.009" MAX WAFER DIA	3670 3223 1300	3670-AT
SCRIBING MACHINE, SEMICONDUCTOR WAFER, DIAMOND TOOL TYPE, AUTOMATIC	1 SCRIBING HD 3.250" THRU 3.259" MAX WAFER DIA	3670 3223 1325	3670-AT
SCRIBING MACHINE, SEMICONDUCTOR WAFER, DIAMOND TOOL TYPE, MANUALLY OPERATED		3670 3221 0000	3670-AT
SCRIBING MACHINE, SEMICONDUCTOR WAFER, DIAMOND TOOL TYPE, MANUALLY OPERATED	1 SCRIBING HD 1.500" THRU 1.509" MAX WAFER DIA	3670 3221 1150	3670-AT
SCRIBING MACHINE, SEMICONDUCTOR WAFER, DIAMOND TOOL TYPE, SEMI-AUTOMATIC		3670 3222 0000	3670-AT
SCRIBING MACHINE, SEMICONDUCTOR WAFER, LASER BEAM TYPE, AUTOMATIC		3670 3226 0000	3670-AT
SCRIBING MACHINE SEMICONDUCTOR WAFER, LASER BEAM TYPE, MANUALLY OPERATED		3670 3224 0000	3670-AT
SCRIBING MACHINE, SEMICONDUCTOR WAFER, LASER BEAM TYPE, NUMERICALLY CONTROLLED		3670 3227 0000	3670-YY
SCRIBING MACHINE, SEMICONDUCTOR WAFER, LASER BEAM TYPE, SEMI-AUTOMATIC		3670 3225 0000	3670-AT
SEALING AND BACK FILLING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC		3670 3391 0000	3670-YY
SEALING AND EXHAUST MACHINE, SEMICONDUCTOR DEVICE		3670 3392 0000	3670-YY
SEALING MACHINE, SEMICONDUCTOR DEVICE, FLAT PACK		3670 3381 0000	3670-YY
SEALING MACHINE, SEMICONDUCTOR DEVICE, GLASS DIODE		3670 3382 0000	3670-YY
SEALING MACHINE, SEMICONDUCTOR DEVICE, TRANSISTOR CAN		3670 3383 0000	3670-YY
SLOTING MACHINE, PRINTED CIRCUIT BOARD, HORIZONTAL SPINDLE		3670 1212 0000	3670-AD
SLOTING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, VERTICAL, NUMERICALLY CONTROLLED		3670 1217 0000	3670-AW
SLOTING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, VERTICAL, NUMERICALLY CONTROLLED	2.000" THRU 2.099" MAX STROKE 15" THRU 15-7/8" THROAT DEPTH	3670 1217 2015	3670-AW
SLOTING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, VERTICAL, NUMERICALLY CONTROLLED	3.000" THRU 3.099" MAX STROKE 26" THRU 26-7/8" THROAT DEPTH	3670 1217 3026	3670-AW
SLOTING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, VERTICAL, NUMERICALLY CONTROLLED	4.000" THRU 4.099" MAX STROKE 4" THRU 4-7/8" THROAT DEPTH	3670 1217 4040	3670-AW
SLOTING MACHINE, PRINTED CIRCUIT BOARD, VERTICAL SPINDLE		3670 1211 0000	3670-AE
SLOTING MACHINE, PRINTED CIRCUIT BOARD, VERTICAL SPINDLE	2.500" THRU 2.599" MAX STROKE 12" THRU 12-7/8" THROAT DEPTH	3670 1211 2512	3670-AE
SOLDER WRAPPING MACHINE, SEMICONDUCTOR DEVICE		3670 35710000	3670-YY
STRAIGHTENING MACHINE, AXIAL LEAD		3670 2113 0000	3670-YY
STRAIGHTENING MACHINE, RADIAL LEAD		3670 2123 0000	3670-YY
STRIPPER-ETCHER, PHOTO RESIST, SEMICONDUCTOR WAFER, PLASMA DRY ASHING TYPE		3670 3343 0000	3670-BJ
STRIPPER-ETCHER, PHOTO RESIST, SEMICONDUCTOR WAFER, PLASMA DRY ASHING TYPE	1 CHAMBER 5" THRU 5-7/8" ID X 8" THRU 8-7/8" LG	3670 3343 1508	3670-BJ
STRIPPER-ETCHER, PHOTO RESIST, SEMICONDUCTOR WAFER, PLASMA DRY ASHING TYPE	1 CHAMBER 8" THRU 8-7/8" ID X 8" THRU 8-7/8" LG	3670 3343 1808	3670-BJ
STRIPPER, PHOTO RESIST, SEMICONDUCTOR WAFER, PLASMA DRY ASHING TYPE	1 CHAMBER	3670 3341 0000	3670-BJ

Section 1-NOMENCLATURE TO PEC

Description	Size or Capacity	Plant Equipment Code	Descriptive Guide No.
STRIPPER, PHOTO RESIST, SEMICONDUCTOR WAFER, PLASMA DRY ASHING TYPE	1 CHAMBER 3" THRU 3-7/8" ID X 6" THRU 6-7/8" LG CHAMBER	3670 3341 1306	3670-BJ
STRIPPER, PHOTO RESIST, SEMICONDUCTOR WAFER, PLASMA DRY ASHING TYPE	1 CHAMBER 4" THRU 4-7/8" ID X 8" THRU 8-7/8" LG CHAMBER	3670 3341 1408	3670-BJ
STRIPPER, PHOTO RESIST, SEMICONDUCTOR WAFER, PLASMA DRY ASHING TYPE	1 CHAMBER 7" THRU 7-7/8" ID X 12" THRU 12-7/8" LG CHAMBER	3670 3341 1712	3670-BJ
STRIPPER, PHOTO RESIST, SEMICONDUCTOR WAFER, PLASMA DRY ASHING TYPE	1 CHAMBER 8" THRU 8-7/8" ID X 8" THRU 8-7/8" LG CHAMBER	3670 3341 1808	3670-BJ
STRIPPER, PHOTO RESIST, SEMICONDUCTOR WAFER, PLASMA DRY ASHING TYPE	1 CHAMBER 9" AND OVER ID X 21 THRU 21-7/8" LG CHAMBER	3670 3341 1921	3670-BJ
STRIPPER, PHOTO RESIST, SEMICONDUCTOR WAFER, PLASMA DRY ASHING TYPE	2 CHAMBERS 4" THRU 4-7/8" ID X 8" THRU 8-7/8" LG CHAMBER	3670 3341 2408	3670-BJ
*TEST AND SORT MACHINE, TRANSISTOR		3670 3715 0000	3670-YY
TEST AND SORT SYSTEM, CHIP, BEAM LEAD		3670 3526 0000	3670-YY
TEST SYSTEM, IMPURITY CONCENTRATION, SEMICONDUCTOR WAFER		3670 3523 0000	3670-YY
TEST SYSTEM, SURFACE CLEANLINESS, PRINTED CIRCUIT ASSEMBLY		3670 3712 0000	3670-YY
TEST SYSTEM, TEMPERATURE CONTROLLED, ELECTRONIC COMPONENT		3670 3711 0000	3670-YY
TESTER, PLATED THRU-HOLE, PRINTED CIRCUIT BOARD		3670 1421 0000	3670-YY
TESTER, SHOCK, ELECTRONIC COMPONENT, ACCELERATION TYPE		3670 3529 0000	3670-YY
TRIMMING MACHINE, LEAD, PRINTED CIRCUIT BOARD		3670 2132 0000	3670-AJ
TRIMMING MACHINE, MICRORESISTOR, ABRASIVE BLAST TYPE		3670 3361 0000	3670-YY
TRIMMING MACHINE, MICRORESISTOR, LASER BEAM TYPE		3670 3362 0000	3670-YY
UNPLUGGING MACHINE, CAPILLARY, WIRE BONDER		3670 3911 0000	3670-YY
WINDING MACHINE, POTENTIOMETER CARD		3670 2129 0000	3670-YY

Section 2-EQUIPMENT DESCRIPTION BY MFR

Manufacturer's Designation	Description	Size or capacity	Plant equip code
5300S	ADCOTECH CORPORATION SUNNYVALE, CALIFORNIA MFR FED CODE 59107 STRAIGHTENING MACHINE, RADIAL LEAD		3670 2123 0000
4000	ADVANCE PROCESS SUPPLY CO. CHICAGO, ILLINOIS MFR FED CODE 29431 PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	14-1/2" MAX PRINT W 22-3/4" MAX PRINT LG	3670 1342 1422
TRUDRIL75-4	ADVANCED CONTROLS CORP. ANAHEIM, CALIFORNIA MFR FED CODE 50511 DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	013" MIN DRILL DIA 187" MAX DRILL DIA 12" W X 24" LG MAX BOARD	3670 1123 2736
101PA	ADVANCED EQUIPMENT COMPANY, INC. CAPITOL HEIGHTS, MARYLAND MFR FED CODE 94011 COATING MACHINE, PRINTED CIRCUIT BOARD, SPRAY TYPE, AUTOMATIC		3670 1282 0000
CBDI 181	AERONUTRONIC FORD CORP. ELECTRONICS DIV. SEE: FORD AEROSPACE AND COMMUNICATIONS CORP. ELECTRONICS DIV. MFR FED CODE 87216		
D5250	AETNA MANUFACTURING CO. BENSENVILLE, ILLINOIS MFR FED CODE 92800 DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, SEMI-AUTOMATIC	010" MIN DRILL DIA 250" MAX DRILL DIA	3670 1111 1812
ACROROUTER	DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, SEMI-AUTOMATIC 12" THROAT DEPTH	010" MIN DRILL DIA 250" MAX DRILL DIA	3670 1111 1812
	SLOTTING MACHINE, PRINTED CIRCUIT BOARD, VERTICAL SPINDLE	2-1/2" MAX STROKE 12" THROAT DEPTH	3670 1211 2512
M22A	AFFILIATED MANUFACTURERS, INC. SERIGRAPHICO DIV. NORTH BRANCH, NEW JERSEY MFR FED CODE 29609	2" MAX PRINT W 2" MAX PRINT LG	3670 1342 0202
MA12	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	3" MAX PRINT W	3670 1342 0303
MAI2BBRH	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	3" MAX PRINT LG	3670 1342 0505
0P645	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	5" MAX PRINT W	3670 1342 0505
462	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	5-1/2" MAX PRINT LG	3670 1342 0505
C53	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	5" MAX PRINT W	3670 1342 0606
CP88	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, AUTOMATIC	6" MAX PRINT W	3670 1343 0405
CP885	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, AUTOMATIC	6" MAX PRINT LG	3670 1343 0808
885	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE AUTOMATIC	8" MAX PRINT W	3670 1343 0808
	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE AUTOMATIC	8" MAX PRINT LG	3670 1343 1212
330	AFFILIATED MANUFACTURERS, INC. PRESCO DIVISION NORTH BRANCH, NEW JERSEY MFR FED CODE 21422	12" MAX PRINT W 12" MAX PRINT LG	3670 1343 1212
435	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	3" MAX PRINT W	3670 1342 0303
251	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	3" MAX PRINT LG	3670 1342 0304
CP645	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	4" MAX PRINT LG	3670 1342 0406
782	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	4-1/2" MAX PRINT W	3670 1342 0406
OO1C	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	6" MAX PRINT LG	3670 1342 0505
200	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	5" MAX PRINT W	3670 1342 0505
	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	5" MAX PRINT LG	3670 1342 0505
	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	5" MAX PRINT W	3670 1342 0606
	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	6" MAX PRINT W	3670 1342 0606
	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	6" MAX PRINT LG	3670 1342 0606

Section 2-EQUIPMENT DESCRIPTION BY MFR

Manufacturer's Designation	Description	Size or capacity	Plant equip code
500	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	6" MAX PRINT W 6" MAX PRINT LG	3670 1342 0606
AMS8	ALESSI INDUSTRIES COSTA MESA, CALIFORNIA MFR FED CODE 50093	8 MAX PROBE HDS 2" X AXIS TVL 2" Y AXIS TVL	3670 3111 0833
ATS	PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	9 MAX PROBE HDS 2" X AXIS TVL 2" Y AXIS TVL	3670 3111 0933
RELA000	TEST SYSTEM, TEMPERATURE CONTROLLED, ELECTRONIC COMPONENT		3670 3711 0000
IONOGRAPH	ALPHA METALS, INC. JERSEY CITY, NEW JERSEY MFR FED CODE 96613		3670 3712 0000
XAT 71L	TEST SYSTEM, SURFACE CLEANLINESS, PRINTED CIRCUIT ASSEMBLY		3670 3362 0000 3670 3362 0000
AMV800	APOLLO LASERS, INC. LOS ANGELES, CALIFORNIA MFR FED CODE 32141	24 MAX WAFERS 1.250" MAX WAFER DIA	3670 3442 2412
AMS2600	REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, DUAL CHAMBER	18 MAX WAFERS 2.000" MAX WAFER DIA	3670 3452 1820
914	REACTOR, SILICON OXIDE, SEMICONDUCTOR WAFER, BATCH TYPE	APPLIED PROCESS TECHNOLOGY, INC. SANTA CLARA, CALIFORNIA MFR FED CODE 51410	
PC3200	PROCESSING MACHINE, PRINTED CIRCUIT BOARD, MULTI-OPERATION	5" MAX PANEL W 5" MAX PANEL LG	3670 1371 0505
HP1500	ARGUS INTERNATIONAL HOPEWELL, NEW JERSEY MFR FED CODE 51259	20" MAX PANEL W	3670 1245 2000
HP1502	CLEANING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE	3-1/2" MAX PANEL W	3670 1392 0300
HP1522	FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, DOUBLE SIDE	3" MAX PANEL W	3670 1392 0300
PC4020A	FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, DOUBLE SIDE	3-1/2" MAX PANEL W	3670 1392 0300
PC4200	FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, DOUBLE SIDE	10" MAX PANEL W	3670 1392 1000
PC4520	FUSING MACHINE, INFRARED, PRINTED CIRCUIT BOARD, DOUBLE SIDE	20" MAX PANEL W	3670 1392 2000
RICHMARK CAM ERA SER	ARMY, DEPARTMENT OF THE WASHINGTON, D. C. MFR FED CODE 99994	187" MIN PUNCH DIA 250" MAX PUNCH DIA 23" W X 29" LG MAX BOARD	3670 1141 7867
172 8036	PUNCHING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, SEMI-AUTOMATIC	4" MAX STROKE 4" THROAT DEPTH	3670 1217 4040
UF	SLOTING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, VERTICAL, NUMERICALLY CONTROLLED		3670 2132 0000 3670 3711 0000
BWLPAI000 BWLpdb2000	TRIMMING MACHINE, LEAD, PRINTED CIRCUIT BOARD		3670 3153 0000
	TEST SYSTEM, TEMPERATURE CONTROLLED, ELECTRONIC COMPONENT		3670 3527 0000 3670 3527 0000
	AXION CORP. DANBURY, CONNECTICUT MFR FED CODE 27654		
	BONDING MACHINE, FLIP CHIP, SEMICONDUCTOR DEVICE, ULTRASONIC TYPE		
	B AND W ENGINEERING SERVICES COSTA MESA, CALIFORNIA MFR FED CODE 57898		
	DETECTOR, LOOSE PARTICLE, ELECTRONIC COMPONENT		
	DETECTOR, LOOSE PARTICLE, ELECTRONIC COMPONENT		

Section 2-EQUIPMENT DESCRIPTION BY MFR

Manufacturer's Designation	Description	Size or capacity	Plant equip code
CRD854D	B T U ENGINEERING CORP. NORTH BILLERICA, MASSACHUSETTS MFR FED CODE 08651 DRYING MACHINE, PRINTED CIRCUIT BOARD, HORIZONTAL CONVEYOR TYPE	8" MAX PANEL W	3670 1272 0800
V0827120N60	DRYING MACHINE, PRINTED CIRCUIT BOARD, HORIZONTAL CONVEYOR TYPE	8" MAX PANEL W.	3670 1272 0800
802E	BARNABY MFG. CO., INC. BRIDGEPORT, CONNECTICUT MFR FED CODE 95568 DRILLING AND PINNING MACHINE, PRINTED CIRCUIT BOARD		3670 1160 0000
42-75-01	BARON-BLAKESLEE DIV. PUREX CORP. SEE: PUREX CORP. BARON-BLAKESLEE DIV. MFR FED CODE 25233 BAUSCH AND LOMB, INC. ROCHESTER, NEW YORK MFR FED CODE 06175 INSPECTION MACHINE, PRINTED CIRCUIT BOARD, OPTICAL COMPARATOR TYPE	12" MAX PANEL W 12" MAX PANEL LG	3670 1423 1212
SCC100P	BENDIX CORP. ELECIRIC AND FLUID POWER DIV. ELECTRIC POWER FACILITY EATON TOWN, NEW JERSEY MFR FED CODE 83298 PATTERN GENERATOR, PHOTOMASK, SEMICONDUCTOR WAFER, NUMERICALLY CONTROLLED		3670 3533 0000
73-605	BIDDLE JAMES G., COMPANY BLUE BELL, PENNSYLVANIA MFR FED CODE 07239 CONTROL AND CALIBRATE UNIT, MICRORESISTOR TRIMMING MACHINE		3670 3371 0000
75-4310	CONTROL AND CALIBRATE UNIT, MICRORESISTOR TRIMMING MACHINE		3670 3371 0000
20	BILLCO MANUFACTURING, INC. ZELIENOPLE, PENNSYLVANIA MFR FED CODE 17947 CLEANING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE	20" MAX PANEL W	3670 1235 2000
712	CLEANING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, BRUSH TYPE	24" MAX PANEL W	3670 1245 2400
LVS	BOWATER-SCOTT CORPORATION, LTD. BOWATER-SCOTT HOUSE WEST SUSSEX, ENGLAND MFR FED CODE K5622 TEST SYSTEM, IMPURITY CONCENTRATION, SEMICONDUCTOR WAFER		3670 3523 0000
FPA141	CANON CAMERA COMPANY, INCORPORATED TOKYO, JAPAN MFR FED CODE S3374 ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, AOTOMATIC	5" W X 6" LG 3.000" MAX WAFER DIA	3670 3263 5730
SP390750	PHOTOMASK MACHINE, STEP AND REPEAT, AUTOMATIC POSITIONING		3670 3513 0000
1300	CHEMCUT CORP. STATE COLLEGE, PENNSYLVANIA MFR FED CODE 08514 CLEANING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE, SPRAY TYPE	15" MAX PANEL W	3670 1236 1500
601-20	DEBURRING RINSING AND DRYING MACHINE, PRINTED CIRCUIT BOARD, DOUBLE SIDE	20" MAX PANEL W 250" MAX PANEL THK	3670 1255 2025
547-30	DRYING MACHINE, PRINTED CIRCUIT BOARD, HORIZONTAL CONVEYOR TYPE	30" MAX PANEL W	3670 1272 3000
1100	DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, MANUAL LOAD	24" MAX PANEL W 26" MAX PANEL LG	3670 1331 2426
547-15	DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, HORIZONTAL CONVEYOR TYPE	15" MAX PANEL W 250" MAX PANEL THK	3670 1334 1525
547	CLEANING SYSTEM, PRINTED CIRCUIT BOARD, MODULAR, SPRAY TYPE	20" MAX PANEL W	3670 1511 2000
M81 ID3	CLEANING SYSTEM, PRINTED CIRCUIT BOARD, MODULAR, SPRAY TYPE	30" MAX PANEL W	3670 1511 3000
547	CLEANING SYSTEM, PRINTED CIRCUIT BOARD, MODULAR, SPRAY TYPE	30" MAX PANEL W	3670 1511 3000

Section 2-EQUIPMENT DESCRIPTION BY MFR

Manufacturer's Designation	Description	Size or capacity	Plant equip code
ITRONAUTOMAT IC	PRINTING SYSTEM, PRINTED CIRCUIT BOARD, SCREEN TYPE CIRCUIT EQUIPMENT CORPORATION FOREST HILL, MARYLAND MFR FED CODE 59126	15" MAX PRINT W 24" MAX PRINT LG	3670 1515 1524
CYCLOPS-2	INSPECTION MACHINE, PRINTED CIRCUIT BOARD, OPTICAL COMPARATOR TYPE CLAIR MANUFACTURING COMPANY, INCORPORATED SUB OF CHROMALLOY AMERICAN CORPORATION OLEAN, NEW YORK MFR FED CODE 80412		3670 1423 0000
42PS	POLISHING MACHINE, PRINTED CIRCUIT BOARD, DRUM TYPE COBILT DIV. COMPUTERVISION CORP. SEE: COMPUTERVISION COBILT DIV. MFR FED CODE 52899 COHERENT, INC. PALO ALTO, CALIFORNIA MFR FED CODE 28845	18" MAX PANEL W 3" MAX PANEL THK	3670 1221 1830
DMVLSUPERPOW ER	TRIMMING MACHINE, MICRORESISTOR, LASER BEAM TYPE COLIGHT INCORPORATED MINNEAPOLIS, MINNESOTA MFR FED CODE 06600		3670 3362 0000
SYSTEM-V	EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	20" MAX PANEL W 24" MAX PANEL LG	3670 1325 2024
SCANEX2	EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	24" MAX PANEL W 25" MAX PANEL LG.	3670 1325 2425
SCANEX2	EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE COMCO, INC. BURBANK, CALIFORNIA MFR FED CODE 50325	30" MAX PANEL W 40" MAX PANEL LG	3670 1325 3040
MB100	EXPOSURE UNIT, PRINTED CIRCUIT BOARD, DOUBLE SIDE, FRAME TYPE	30" MAX PANEL W 72" MAX PANEL LG	3670 1325 3072
MB102	TRIMMING MACHINE, MICRORESISTOR, ABRASIVE BLAST TYPE		3670 3361 0000
MT100	TRIMMING MACHINE, MICRORESISTOR, ABRASIVE BLAST TYPE COMMONWEALTH SCIENTIFIC CORP. ALEXANDRIA, VIRGINIA MFR FED CODE 51393		3670 3361 0000
MILLATRON4	ETCHING MACHINE, ION BEAM, SEMICONDUCTOR WAFER COMPUTERVISION COBILT DIV. SANTA CLARA, CALIFORNIA MFR FED CODE 52899		3670 3355 0000
CA400	ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	4" W X 5" LG MAX MASK 4" MAX WAFER DIA	3670 3262 5640
CA400A	ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	4" W X 5" LG MAX MASK 4" MAX WAFER DIA	3670 3262 5640
CA2020H	ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	5" W X 5" LG MAX MASK 4" MAX WAFER DIA	3670 3262 6640
CA800	ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	5" W X 5" LG MAX MASK 4" MAX WAFER DIA	3670 3262 6640
28	ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC CURTIN-HEBERT CO., INC. GLOVERSVILLE, NEW YORK MFR FED CODE 94871	5" W X 5" LG MAX MASK 4" MAX WAFER DIA	3670 3262 6640
631	POLISHING MACHINE, PRINTED CIRCUIT BOARD, DRUM TYPE DAC CARPINTERIA, CALIFORNIA MFR FED CODE 23574	15" MAX PANEL W 1" MAX PANEL THK	3670 1221 1510
C34646	DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI- SPINDLE, NUMERICALLY CONTROLLED	013" MIN DRILL DIA 187" MAX DRILL DIA	3670 1123 2700
DR3	DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI- SPINDLE, NUMERICALLY CONTROLLED	013" MIN DRILL DIA 250" MAX DRILL DIA 20" W X 20" LG MAX BOARD	3670 1123 2855

Section 2-EQUIPMENT DESCRIPTION BY MFR

Manufacturer's Designation	Description	Size or capacity	Plant equip code
9001-36-36-3 6	DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI SPINDLE, NUMERICALLY CONTROLLED	040" MIN DRILL DIA 187" MAX DRILL DIA 12" W X 18" LG MAX BOARD	3670 1123 3735
MARKSIX	DATA-CONTROL SYSTEMS DIV OF GENERAL INDICATOR CORPORATION SUB OF COMPUDYNE CORPORATION DANBURY, CONNECTICUT MFR FED CODE 08539 PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	10 MAX PROBE HDS 1.500" X AXIS TVL 1.500" Y AXIS TVL	3670 3111 1022
060	DAYMARC, CORP. WALTHAM, MASSACHUSETTS MFR FED CODE 27987 PROBING STATION, SEMICONDUCTOR DEVICE, FIXED PATTERN TYPE		3670 3114 0000
SPSA5	DE HAART, INC. BURLINGTON, MASSACHUSETTS MFR FED CODE 34645 PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	5" MAX PRINT W 5" MAX PRINT LG	3670 1342 0505
RT3C	TRIMMING MACHINE, MICRORESISTOR, ABRASIVE BLAST TYPE		3670 3361 0000
RT3D	TRIMMING MACHINE, MICRORESISTOR, ABRASIVE BLAST TYPE		3670 3361 0000
8036	DELTA DESIGN, INCORPORATED SAN DIEGO, CALIFORNIA MFR FED CODE 59444 TEST SYSTEM, TEMPERATURE CONTROLLED, ELECTRONIC COMPONENT		3670 3711 0000
WAC01000	DEVELOP-AMATIC ENGINEERING, INC. SEE: MC CORMICK AUTOMATICS CO. MFR FED CODE 04841 DEVELOPMENT ASSOCIATES CONTROLS SEE: DAC MFR FED CODE 23574		
7001	DIGITAL SYSTEMS, INC. ARCADIA, CALIFORNIA MFR FED CODE 19466 DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, SEMI-AUTOMATIC	013" MIN DRILL DIA 156" MAX DRILL DIA 12-1/4" THROAT DEPTH	3670 1111 2712
7001	DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	010" MIN DRILL DIA 125" MAX DRILL DIA 10" W X 17" LG MAX BOARD	3670 1123 1635
6803	DRILLING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, NUMERICALLY CONTROLLED	013" MIN DRILL DIA 250" MAX DRILL DIA 14" W X 20" LG MAX BOARD	3670 1123 2845
3060	LAYOUT AND DRILLING MACHINE, PRINTED CIRCUIT BOARD, NUMERICALLY CONTROLLED	030" MIN DRILL DIA 250" MAX DRILL DIA 16" W X 47" LG MAX BOARD	3670 1123 3849
IPC4000PC	DIONEX CORP. GAS PLASMA SYSTEMS HAYWARD, CALIFORNIA MFR FED CODE 51505 REACTOR, ETCHING, PLASMA, SEMICONDUCTOR WAFER, SINGLE CHAMBER	013" MIN DRILL DIA 250" MAX DRILL DIA 20" W X 20" LG MAX BOARD	3670 1153 2855
8000	REACTOR, ETCHING, PLASMA, SEMICONDUCTOR WAFER, SINGLE CHAMBER		3670 3453 0000
8200	REACTOR, ETCHING, PLASMA, SEMICONDUCTOR WAFER, SINGLE CHAMBER		3670 3453 0000
L10	DIPEC MEMPHIS, TENNESSEE MFR FED CODE 99998 PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	8" MAX PRINT W 10" MAX PRINT LG	3670 1343 0810
1021	DONOVAN INDUSTRIES SCOTIA, NEW YORK MFR FED CODE 52398 PROCESSING MACHINE, PRINTED CIRCUIT BOARD, MULTI-OPERATION		3670 1371 0000
	DORN ERNEST W., CO., INC. GARDENA, CALIFORNIA MFR FED CODE 27635		


Section 2-EQUIPMENT DESCRIPTION BY MFR

Manufacturer's Designation	Description	Size or capacity	Plant equip code
FCP1224A	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, SEMI-AUTOMATIC	12" MAX PRINT W	3670 1342 1218
33A120	PRINTER, PRINTED CIRCUIT BOARD, SCREEN TYPE, AUTOMATIC	18" MAX PRINT LG	3670 1343 0303
0112-5	DOSIER, PAUL, ASSOCIATES, INC. COSTA MESA, CALIFORNIA MFR FED CODE 54140	3" MAX PRINT W	
0113-4	SLOTING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, VERTICAL, NUMERICALLY CONTROLLED	3" MAX PRINT LG	
0113-4	SLOTING MACHINE, PRINTED CIRCUIT BOARD, MULTI-SPINDLE, VERTICAL, NUMERICALLY CONTROLLED	2" MAX STROKE	3670 1217 2015
B	DU PONT, E.I. DE NEMOURS AND CO., INC. WILMINGTON, DELAWARE MFR FED CODE 18873	15" THROAT DEPTH	3670 1217 3026
B	LAMINATOR, FILM RESIST, ROLLER TYPE, HEATED	3" MAX STROKE	3670 1217 3026
HRL24	LAMINATOR, FILM RESIST, ROLLER TYPE, HEATED	26-1/4" THROAT DEPTH	
PC30	DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, MANUAL LOAD	18" MAX PANEL W	3670 1311 1825
C	DEVELOPER, PHOTO RESIST, PRINTED CIRCUIT BOARD, SOLVENT SPRAY, HORIZONTAL CONVEYOR TYPE	.250" MAX PANEL THK	3670 1311 2625
CAP24	DEVELOPER-RINSE, DRYER, PHOTO RESIST, PRINTED CIRCUIT BOARD, HORIZONTAL CONVEYOR TYPE	.250" MAX PANEL THK	3670 1311 2625
CAP24	DUMAS INSTRUMENTS CO., DIV. SEMIMETALS, INC. SEE: SEMIMETALS, INC. - WESTERN DIV. MFR FED CODE 25544	30" MAX PANEL W	3670 1331 3024
250	DYNACHEM CORP. TUSTIN, CALIFORNIA MFR FED CODE 15114	24" MAX PANEL LG	3670 1334 2437
250	LAMINATOR, FILM RESIST, ROLLER TYPE, HEATED	375" MAX PANEL THK	3670 1336 2425
ARTMECH	LAYOUT AND DRILLING MACHINE, PRINTED CIRCUIT BOARD, SEMI-AUTOMATIC	24" MAX PANEL W	3670 1336 2425
2000C	PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	25" MAX PANEL W	3670 1311 2537
2001C	E-SYSTEMS, INC. MELPAR DIV. FALLS CHURCH, VIRGINIA MFR FED CODE 04071	.375" MAX PANEL THK	
2001	LAYOUT AND DRILLING MACHINE, PRINTED CIRCUIT BOARD, SEMI-AUTOMATIC	013" MIN DRILL DIA	3670 1151 2723
2504	PROBING MACHINE, SEMICONDUCTOR DEVICE, MANUALLY OPERATED	156" MAX DRILL DIA	3670 3111 1400
2510	EATON CORPORATION SEMICONDUCTOR WAFER SYSTEMS DIVISION SUNNYVALE, CALIFORNIA MFR FED CODE 51510	8" W X 12" LG MAX BOARD	3670 3111 1400
2000C	ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	14 MAX PROBE HDS	
2001C	ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	4" W X 5" LG MAX MASK	3670 3262 5635
2001	ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	3.500" MAX WAFER DIA	3670 3262 5635
2504	ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR WAFER, AUTOMATIC	4" W X 5" LG MAX MASK	3670 3263 5635
2510	PHOTOMASK MACHINE, STEP AND REPEAT, SEMI-AUTOMATIC POSITIONING	3.500" MAX WAFER DIA	3670 3512 0303
UF28FB	PHOTOMASK MACHINE, STEP AND REPEAT, SEMI-AUTOMATIC POSITIONING	3" MAX MASK W	3670 3512 0303
410	ECCO HIGH FREQUENCY CORP. NORTH BERGEN, NEW JERSEY MFR FED CODE 19234	3" MAX MASK LG	3670 3512 0303
410	REACTOR, EPITAXIAL, SEMICONDUCTOR WAFER, DUAL CHAMBER	8 MAX WAFERS	3670 3442 0815
120	EG AND G., INC. WELLESLEY HILLS, MASSACHUSETTS MFR FED CODE 92678	1.5" MAX WAFER DIA	
44	TEST SYSTEM, TEMPERATURE CONTROLLED, ELECTRONIC COMPONENT	013" MIN DRILL DIA	3670 3711 0000
44	ELECTRO MECHANO CO. MILWAUKEE, WISCONSIN MFR FED CODE 80300	250" MAX DRILL DIA	3670 1111 2810
44	DRILLING MACHINE, PRINTED CIRCUIT BOARD, SINGLE SPINDLE, SEMI-AUTOMATIC	10" THROAT DEPTH	
44	ELECRO SCIENTIFIC INDUSTRIES, INC. PORTLAND, OREGON MFR FED CODE 11837	TRIMMING MACHINE, MICRORESISTOR, LASER BEAM TYPE	3670 3362 0000

Section 2-EQUIPMENT DESCRIPTION BY MFR

Manufacturer's Designation	Description	Size or capacity	Plant equip code
131B	ELECTROGLAS, INC. SANTA CLARA, CALIFORNIA MFR FED CODE 25959 PROBING MACHINE, SEMICONDUCTOR DEVICE, SEMI-AUTOMATIC	20 MAX PROBE HDS 1.800" X AXIS TVL 1.800" Y AXIS TVL	3670 3112 2022
920	PROBING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC	18 MAX PROBE HDS 2" X AXIS TVL 2" Y AXIS TVL	3670 3113 1833
920SS	PROBING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC	18 MAX PROBE HDS 2" X AXIS TVL 2" Y AXIS TVL	3670 3113 1833
900A	PROBING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC	20 MAX PROBE HDS 2" X AXIS TVL 2" Y AXIS TVL	3670 3113 2033
910	PROBING MACHINE, SEMICONDUCTOR DEVICE, AUTOMATIC	24 MAX PROBE HDS 2.300" X AXIS TVL 2.300" Y AXIS TVL	3670 3113 2433
1034X	PROBING STATION, SEMICONDUCTOR DEVICE, FIXED PATTERN TYPE		3670 3114 0000
SP2	BONDING MACHINE, WIRE, SEMICONDUCTOR DEVICE, THERMOCOMPRESSION TYPE		3670 3122 0000
500D	ALIGNMENT MACHINE, MASK, SEMICONDUCTOR WAFER, SEMI-AUTOMATIC	2" W X 2" LG MAX MASK	3670 3252 3321
0MA360	ALIGNMENT AND EXPOSURE MACHINE, MASK, SEMICONDUCTOR	2.100" MAX WAFER DIA 2" W X 2" LG MAX MASK 2.000 MAX WAFER DIA	3670 3261 3320

RECOMMENDED CHANGES TO EQUIPMENT TECHNICAL PUBLICATIONS

 <div style="border: 1px solid black; border-radius: 15px; padding: 5px; display: inline-block; margin-left: 10px;"> <p style="margin: 0;"><i>THEN...JOT DOWN THE DOPE ABOUT IT ON THIS FORM. CAREFULLY TEAR IT OUT, FOLD IT AND DROP IT IN THE MAIL.</i></p> </div>		SOMETHING WRONG WITH PUBLICATION		
		FROM: (PRINT YOUR UNIT'S COMPLETE ADDRESS)		
PUBLICATION NUMBER		DATE SENT		
PUBLICATION DATE		PUBLICATION TITLE		
BE EXACT PIN-POINT WHERE IT IS				
PAGE NO.	PARA- GRAPH	FIGURE NO.	TABLE NO.	<p style="text-align: center; font-weight: bold;">IN THIS SPACE, TELL WHAT IS WRONG AND WHAT SHOULD BE DONE ABOUT IT.</p>
PRINTED NAME, GRADE OR TITLE AND TELEPHONE NUMBER			SIGN HERE	

The Metric System and Equivalents

Linear Measure

1 centimeter = 10 millimeters = .39 inch
 1 decimeter = 10 centimeters = 3.94 inches
 1 meter = 10 decimeters = 39.37 inches
 1 dekameter = 10 meters = 32.8 feet
 1 hectometer = 10 dekameters = 328.08 feet
 1 kilometer = 10 hectometers = 3,280.8 feet

Weights

1 centigram = 10 milligrams = .15 grain
 1 decigram = 10 centigrams = 1.54 grains
 1 gram = 10 decigrams = .035 ounce
 1 decagram = 10 grams = .35 ounce
 1 hectogram = 10 decagrams = 3.52 ounces
 1 kilogram = 10 hectograms = 2.2 pounds
 1 quintal = 100 kilograms = 220.46 pounds
 1 metric ton = 10 quintals = 1.1 short tons

Liquid Measure

1 centiliter = 10 milliliters = .34 fl. ounce
 1 deciliter = 10 centiliters = 3.38 fl. ounces
 1 liter = 10 deciliters = 33.81 fl. ounces
 1 dekaliter = 10 liters = 2.64 gallons
 1 hectoliter = 10 dekaliters = 26.42 gallons
 1 kiloliter = 10 hectoliters = 264.18 gallons

Square Measure

1 sq. centimeter = 100 sq. millimeters = .155 sq. inch
 1 sq. decimeter = 100 sq. centimeters = 15.5 sq. inches
 1 sq. meter (centare) = 100 sq. decimeters = 10.76 sq. feet
 1 sq. dekameter (are) = 100 sq. meters = 1,076.4 sq. feet
 1 sq. hectometer (hectare) = 100 sq. dekameters = 2.47 acres
 1 sq. kilometer = 100 sq. hectometers = .386 sq. mile

Cubic Measure

1 cu. centimeter = 1000 cu. millimeters = .06 cu. inch
 1 cu. decimeter = 1000 cu. centimeters = 61.02 cu. inches
 1 cu. meter = 1000 cu. decimeters = 35.31 cu. feet

Approximate Conversion Factors

<i>To change</i>	<i>To</i>	<i>Multiply by</i>	<i>To change</i>	<i>To</i>	<i>Multiply by</i>
inches	centimeters	2.540	ounce-inches	Newton-meters	.007062
feet	meters	.305	centimeters	inches	.394
yards	meters	.914	meters	feet	3.280
miles	kilometers	1.609	meters	yards	1.094
square inches	square centimeters	6.451	kilometers	miles	.621
square feet	square meters	.093	square centimeters	square inches	.155
square yards	square meters	.836	square meters	square feet	10.764
square miles	square kilometers	2.590	square meters	square yards	1.196
acres	square hectometers	.405	square kilometers	square miles	.386
cubic feet	cubic meters	.028	square hectometers	acres	2.471
cubic yards	cubic meters	.765	cubic meters	cubic feet	35.315
fluid ounces	milliliters	29.573	cubic meters	cubic yards	1.308
pints	liters	.473	milliliters	fluid ounces	.034
quarts	liters	.946	liters	pints	2.113
gallons	liters	3.785	liters	quarts	1.057
ounces	grams	28.349	liters	gallons	.264
pounds	kilograms	.454	grams	ounces	.035
short tons	metric tons	.907	kilograms	pounds	2.205
pound-feet	Newton-meters	1.356	metric tons	short tons	1.102
pound-inches	Newton-meters	.11296			

Temperature (Exact)

°F	Fahrenheit temperature	5/9 (after subtracting 32)	Celsius temperature	°C
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